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IN THE CLAIMS:

1. (Canceled)
2. (Currently Amended) A die as claimed in ~~claim 1~~ claim 11 wherein the pads of the first set are larger in area than the pads of the second set.
3. (Original) A die as claimed in claim 2 wherein the area of each pad of the first set and the first predetermined center-to-center spacing are suitable for flip-chip assembly of the die, and the area of each pad of the second set and the second predetermined center-to-center spacing are suitable for wire bond assembly of the die.
4. (Currently Amended) A die as claimed in ~~claim 1~~ claim 11 wherein the pads of the first and second ~~set~~ sets are disposed in line adjacent one or more edges of the die.
5. (Canceled)
6. (Currently Amended) A die as claimed in ~~claim 5~~ claim 11 wherein the pads of the second set are disposed in one of the two lines.
7. (Original) A die as claimed in any preceding claim wherein the first set of pads is connected to one set of connection points in the integrated circuit, and the second set of pads is connected to another set of connection points in the integrated circuit.

8 - 10 (Canceled)

11. (Previously Presented) An integrated circuit die including first and second sets of conductive pads for enabling external connections to be made to the integrated circuit, there being at least a first predetermined center-to-center spacing between each pad of the first set and the adjacent pad or pads of the first set, and at least a second predetermined center-to-center spacing, less than said first spacing, between each pad of the second set and the adjacent pad or pads of the first and second sets, wherein the pads of the first set are disposed in two lines adjacent one or more edges of the die, the pads of the first set in one of the two lines being disposed in staggered relationship with respect to the pads of the first set in the other of the two lines, and a passivation layer exposing only pads of the first set, or exposing pads of the first and second sets.

12. (Previously Presented) A die as claimed in Claim 11 wherein the pads of the second set are disposed in one of the two lines.